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BOX ISSUE FEE
PATENT
25611-000076/US

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANTS: Se-young JEONG et al. CONF. NO.: 7662
SERIAL NO.: 10/825,199 GROUP: 2818
FILED: April 16, 2004 EXAMINER: Calvin LEE
FOR: **REINFORCED SOLDER BUMP STRUCTURE AND METHOD
FOR FORMING A REINFORCED SOLDER BUMP**

Customer Service Window
Randolph Building
401 Dulany Street
Alexandria, VA 22314
Mail Stop Issue Fee

January 6, 2006

**COMMENTS ON THE EXAMINER'S
STATEMENT OF REASONS FOR ALLOWANCE**

Sir:

In reply to the Examiner's Statement of Reasons for Allowance, provided with the Notice of Allowance dated October 6, 2006, Applicants submit the following comments.

The Examiner recites several elements from the independent claims as not being disclosed in the Moriyama reference as the reason why the claims of the present application are allowable over the prior art of record. Although Applicants agree that the various limitations recited in the claims are not taught or suggested by the prior art of record, whether taken singly or in combination, Applicants wish to emphasize that it is each claim, taken as a whole,

including the interrelationships and interconnections between various claimed elements which is allowable over the prior art of record.

Should there be any outstanding matters that need to be resolved in the present application, the Examiner is respectfully requested to contact John Castellano, Reg. No. 35,094 at the telephone number indicated below.

If necessary, the Commissioner is hereby authorized in this, concurrent, and future replies, to charge payment or credit any overpayment to Deposit Account No. 08-0750 for any additional fees required under 37 C.F.R. § 1.16 or under 37 C.F.R. § 1.17; particularly, extension of time fees.

Respectfully submitted,

HARNESS, DICKEY, & PIERCE, P.L.C.

By: 

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